

Swing3D

High-speed 3D sensor



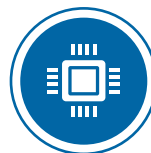
Robotics



Manufacturer



Binpicking

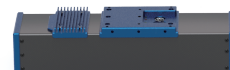
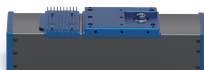


Semiconductor

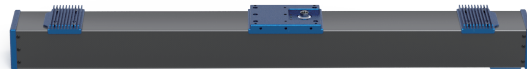
- 1.3 million 3D points
- Rotating line laser allow 3D scans from fixed position
- Top of the line FPGA and DSP
- GenIcam compatible
- Extended FOV support



Specification



Model	Extra Small		Small	
	Normal mode	Extended mode	Normal mode	Extended mode
Clearance distance	405 mm	340 mm	650 mm	540 mm
Measurable depth distance	225 mm	360 mm	360 mm	580 mm
FOV	Near : 256 x 290 mm Far : 268 x 442 mm	Near : 180 x 246 mm Far : 271 x 489 mm	Near : 392 x 463 mm Far : 453 x 704 mm	Near : 284 x 389 mm Far : 472 x 777 mm
3D acquisition time	<1000 mSec		<1000 mSec	
Dimension / Weight	94 x 80 x 307 mm / 1.6kg		94 x 80 x 338 mm / 1.7kg	
Baseline	239 mm		273 mm	



Model	Medium		Large	
	Normal mode	Extended mode	Normal mode	Extended mode
Clearance distance	1200 mm	990 mm	2300 mm	1900 mm
Measurable depth distance	670 mm	1090 mm	1280 mm	2100 mm
FOV	Near : 702 x 833 mm Far : 868 x 1290 mm	Near : 511 x 689 mm Far : 921 x 1434 mm	Near : 1334 x 1579 mm Far : 1650 x 2456 mm	Near : 970 x 1304 mm Far : 1755 x 2745 mm
3D acquisition time	<1000 mSec		<1000 mSec	
Dimension / Weight	94 x 80 x 470 mm / 2.2kg		94 x 80 x 832 mm / 2.5kg	
Baseline	403 mm		765 mm	